

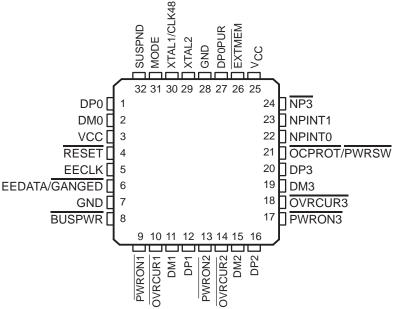
# TUSB2036 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE

SLLS372C - MARCH 2000 - REVISED NOVEMBER 2006

- Fully Compliant With the USB Specification as a Full-Speed Hub: TID #30220242
- Integrated USB Transceivers
- 3.3-V Low-Power ASIC Logic
- One Upstream Port and 2–3 Programmable Downstream Ports
  - Total Number of Ports (2 or 3) Selected by Input Terminal
  - Total Number of Permanently Connected Ports Is Selected by 2 Input Terminals
- Two Power Source Modes
  - Self-Powered Mode
  - Bus-Powered Mode
- All Downstream Ports Support Full-Speed and Low-Speed Operations
- Power Switching and Overcurrent Reporting Is Provided Per Port or Ganged
- Supports Suspend and Resume Operations
- Suspend Status Terminal Available for External Logic Power Down

- Supports Custom Vendor ID and Product ID With External Serial EEPROM
- 3-State EEPROM Interface Allows EEPROM Sharing
- Push-Pull Outputs for PWRON Eliminate the Need for External Pullup Resistors
- Noise Filtering on OVRCUR Provides Immunity to Voltage Spikes
- Supports 6-MHz Operation Through Crystal Input or 48-MHz Input Clock
- Output Terminal Available to Disable External Pullup Resister on DP0 for 3 ms After Reset or After Change on BUSPWR and Enable Easy Implementation of On-Board Bus/Self-Power Dynamic Switching Circuitry
- Available in 32-Terminal LQFP Package
  With a 0.8-mm Terminal Pitch (JEDEC –
  S-PQFP-G For Low-Profile Quad Flat Pack)

VF PACKAGE (TOP VIEW)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# **TUSB2036** 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE

SLLS372C - MARCH 2000 - REVISED NOVEMBER 2006

# description

The TUSB2036 hub is a 3.3-V CMOS device that provides up to three downstream ports in compliance with the USB version 1.1 specification. Because this device is implemented with a digital state machine instead of a microcontroller, no firmware programming is required. Fully-compliant USB transceivers are integrated into the ASIC for all upstream and downstream ports. The downstream ports support both full-speed and low-speed devices by automatically setting the slew rate according to the speed of the device attached to the ports. The configuration of the BUSPWR terminal selects either the bus-powered or the self-powered mode. The introduction of the DP0 pullup resistor disable terminal, DP0PUR, makes it much easier to implement an on-board bus/self-power dynamic-switching circuitry. With the new function terminal, the end-equipment vendor can reduce the total board cost while adding additional product value.

The EXTMEM (terminal 26) enables or disables the optional EEPROM interface. When EXTMEM is high, the vendor and product IDs (VID and PID) use defaults, such that the message displayed during enumeration is General Purpose USB Hub. For this configuration, terminal 6 functions as the GANGED input terminal and the EECLK (terminal 5) is unused. If custom VID and PID descriptors are desired, the EXTMEM must be tied low (EXTMEM = 0) and a SGS Thompson M93C46 EEPROM, or equivalent, stores the programmable VID, PID, and GANGED values. For this configuration, terminals 5 and 6 function as the EEPROM interface signals with terminal 5 as EECLK and terminal 6 as EEDATA, respectively.

The TUSB2036 supports both bus-powered and self-powered modes. External power-management devices such as the TPS2044 are required to control the 5-V power source switching (on/off) to the downstream ports and detect the overcurrent condition from the downstream ports individually or ganged. Outputs from external power devices provide overcurrent inputs to the TUSB2036 OVRCUR terminals in case of an overcurrent condition, the corresponding PWRON terminals are disabled by the TUSB2036. In the ganged mode, all PWRON signals transition simultaneously, and any OVRCUR input can be used. In the nonganged mode, the PWRON outputs and OVRCUR inputs operate on a per-port basis.

The TUSB2036 provides the flexibility of using either a 6-MHz or a 48-MHz clock. The logic level of the MODE terminal controls the selection of the clock source. When MODE is low, the output of the internal APLL circuitry is selected to drive the internal core of the device. When MODE is high, the XTAL1 input is selected as the input clock source and the APLL circuitry is powered down and bypassed. The internal oscillator cell is also powered down while MODE is high. For 6-MHz operation, TUSB2036 requires a 6-MHz clock signal on XTAL1 terminal (with XTAL2 for a crystal) from which its internal APLL circuitry generates a 48-MHz internal clock to sample the data from the upstream port. For 48-MHz operation, the clock cannot be generated with a crystal, using the XTAL2 output, since the internal oscillator cell only supports the fundamental frequency. If low-power suspend and resume are desired, a passive crystal or resonator must be used, although the hub supports the flexibility of using any device that generates a 6-MHz clock. Because most oscillators cannot be stopped while power is on, their use prohibits low-power suspend, which depends on disabling the clock. When the oscillator is used, by connecting its output to the XTAL1 terminal and leaving the XTAL2 terminal open, its TTL output level can not exceed 3.6 V. If a 6-MHz oscillator is used, it must be stopped at a logic low whenever SUSPND is high. For crystal or resonator implementations, the XTAL1 terminal is the input and the XTAL2 terminal is used as the feedback path. A sample crystal-tuning circuit is shown in Figure 7.



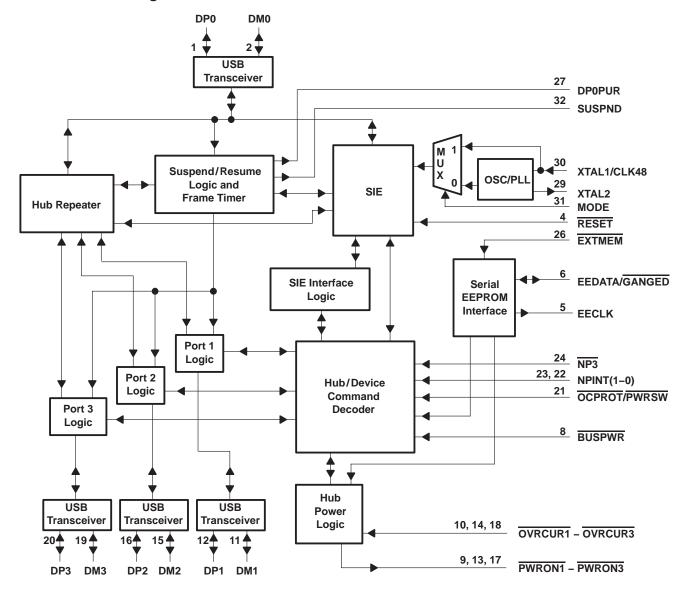
# description (continued)

The hub silicon can accurately reflect the system port configuration by the  $\overline{\text{NP3}}$  and NPINT1-0 terminals. When  $\overline{\text{NP3}}$  is low, the hub is configured as a 3-port hub; when it is high, the hub is configured as a 2-port hub. The NPINT1-0 terminals tell the hub silicon how many ports have permanently attached devices, according to Table 1.

**Table 1. System Port Configuration** 

NPINT1-0	PORT AVAILABILITY	HUB DESCRIPTOR DEVICE REMOVABLE FIELD (7-0)
00	All ports are available through external USB connectors	00000000
01	Port 1 has a permanently attached device; ports 2 and 3 are externally available	0000010
10	Ports 1 and 2 have permanently attached devices; port 3 is externally available	00000110
11	All ports have permanently attached devices	NP3 high: 00000110 NP3 low: 00001110
NPINT1-0	COMPOUND DEVICE OR NOT	HUB DESCRIPTOR WITH HUB CHARACTERISTICS FIELD BIT 2
00	Hub is not part of a compound device	0
01, 10, 11	Hub is part of a compound device	1

# functional block diagram





## **Terminal Functions**

TERMIN	NAL		DECORPTION					
NAME	VF	1/0	DESCRIPTION					
BUSPWR	8	I	Power source indicator. BUSPWR is an active-low input that indicates whether the downstream ports source their power from the USB cable or a local power supply. For the bus-power mode, this terminal must be pulled low, and for the self-powered mode, this terminal must be pulled to 3.3 V. Input must not change dynamically during operation.					
DM0	2	I/O	Root port USB differential data minus. DM0 paired with DP0 constitutes the upstream USB port.					
DM1 – DM3	11, 15, 19	I/O	USB differential data minus. DM1 – DM3 paired with DP1 – DP3 support up to three downstream USB ports.					
DP0	1	I/O	Root port USB differential data plus. DP0 paired with DM0 constitutes the upstream USB port.					
DP0PUR	27	0	Pullup resistor connection. Whenever a system reset occurs (RESET being driven to low, but not USB reset) or any logic level change on BUSPWR terminal, DP0PUR output goes to inactive low until the internal counter reaches a 3-ms time period. After the counter expires, DP0PUR is driven to the V <sub>CC</sub> (3.3 V) level thereafter until the next system reset event or BUSPWR logic level change.					
DP1 – DP3	12, 16, 20	I/O	USB differential data plus. DP1 – DP3 paired with DM1 – DM3 support up to three downstream USB ports.					
EECLK	5	0	EEPROM serial clock. When EXTMEM is high, the EEPROM interface is disabled. The EECLK terminal is disabled and must be left floating (unconnected). When EXTMEM is low, EECLK acts as a 3-state serial clock output to the EEPROM with a 100-μA internal pulldown.					
EEDATA/ GANGED	6	I/O	EEPROM serial data/power management mode indicator. When EXTMEM is high, EEDATA/GANGED selects between ganged and per-port power overcurrent detection for the downstream ports. When EXTMEM is low, EEDATA/GANGED acts as a serial data I/O for the EEPROM and is internally pulled down with a 100-μA pulldown. This standard TTL input must not change dynamically during operation.					
EXTMEM	26	I	EEPROM read enable. When EXTMEM is high, the serial EEPROM interface of the device is disabled. When EXTMEM is low, terminals 5 and 6 are configured as the clock and data terminals of the serial EEPROM interface, respectively.					
GND	7, 28		Ground. GND terminals must be tied to ground for proper operation.					
OCPROT/ PWRSW	21	I	Overcurrent Protection for bus-powered hub (active low). /Power Switching for self-powered hub (active low). The terminal has a different meaning for the bus or self-powered hub. If the terminal is logic high the internal pulldown is disabled. (see Notes 1 and 2).					

## NOTES: 1. If the hub is implemented to be **bus-powered** (via BUSPWR tying to GND):

- TUSB2036 reports to the host that the hub end-product downstream ports are power-switched (this is required by the USB 1.1 specification). Hub end-product vendor has to ensure the actual end-product implementation meets this specification requirement.
- Terminal 21 acts as overcurrent protection (OCPROT) implementation indication terminal for the bus-powered hub. The overcurrent protection implementation is reported through the wHubCharacteristics. D4 bit in the hub descriptor.
- When OCPROT is low, the TUSB2036 reports to the host that the hub end-product provides overcurrent protection and the wHubCharacteristics. D4 bit is set to 0.
- When OCPROT is high, the TUSB2036 reports to the host that the hub end-product does not provide overcurrent protection and the wHubCharacteristics. D4 bit is set to 1.
- 2. If the hub is implemented to be **self-powered** (via  $\overline{\text{BUSPWR}}$  tying to 3.3-V V<sub>CC</sub>):
  - TUSB2036 reports to the host that the hub end-product provides overcurrent protection to the downstream ports (this is required by the USB 1.1 specification). Hub end-product vendor has to ensure the actual end-product implementation meets this specification requirement.
  - Terminal 21 acts as power switching (PWRSW) implementation indication terminal for the self-powered hub. The power-switching implementation is reported through the bPwrOn2PwrGood field in the hub descriptor.
  - When PWRSW is low, the TUSB2036 reports to the host that the hub end-product has port power switching at the downstream ports and the bPwrOn2PwrGood is set to 50 units (100 ms).
  - When PWRSW is high, the TUSB2036 reports to the host that the hub end-product does not have port power switching at the downstream ports and the bPwrOn2PwrGood is set to 0 units (0 ms).



# **TUSB2036** 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE SLLS372C - MARCH 2000 - REVISED NOVEMBER 2006

# **Terminal Functions (Continued)**

TERMINA	<b>AL</b>		
NAME	VF	1/0	DESCRIPTION
OVRCUR1 – OVRCUR3	10, 14, 18	I	Overcurrent input. OVRCUR1 – OVRCUR3 are active low. For per-port overcurrent detection, one overcurrent input is available for each of the three downstream ports. In the ganged mode, any OVRCUR input may be used and all OVRCUR terminals must be tied together. OVRCUR terminals are active low inputs with noise filtering logic. Each OVRCURn input is sampled every 2 ms and any input which is valid for two consecutive samples will be passed to the internal logic. OVRCUR3 has an internal pull-up that can be enabled for the 2-port operation.
PWRON1 – PWRON3	9, 13, 17	0	Power-on/-off control signals. PWRON1 – PWRON3 are active low, push-pull outputs. Push-pull outputs eliminate the pullup resistors which open-drain outputs require. However, the external power switches that connect to these terminals must be able to operate with 3.3-V inputs because these outputs cannot drive 5-V signals.
RESET	4	I	Reset. $\overline{\text{RESET}}$ is an active-low TTL input with hysteresis and must be asserted at power up. When $\overline{\text{RESET}}$ is asserted, all logic is initialized. Generally, a reset with a pulse width between 100 $\mu$ s and 1 ms is recommended after 3.3-V V <sub>CC</sub> reaches its 90%. The clock signal must be active during the last 60 $\mu$ s of the reset window.
SUSPND	32	0	Suspend status. SUSPND is an active-high output available for external logic power-down operations. During the suspend mode, SUSPND is high. SUSPND is low for normal operation.
MODE	31	I	Mode select. When MODE is low, the APLL output clock is selected as the clock source to drive the internal core of the device and 6-MHz crystal or oscillator can be used. When MODE is high, the clock on XTAL1/CLK48 is selected as the clock source and 48-MHz oscillator or other on-board clock source can be used.
NP3	24	I	Number of ports is 3. Active low input. A logic 0 configures the system to use 3 ports. A logic 1 configures the system to use 2 ports.
NPINT1-0	23, 22	I	Number of ports internal to hub system, which are permanently attached (see Table 1)
VCC	3, 25		3.3-V supply voltage
XTAL1/CLK48	30	I	Crystal 1/48-MHz clock input. When MODE is low, XTAL1/CLK48 is a 6-MHz crystal input with 50% duty cycle. An internal APLL generates the 48-MHz and 12-MHz clocks used internally by the ASIC logic. When MODE is high, XTAL1/CLK48 acts as the input of the 48-MHz clock and the internal APLL logic is bypassed.
XTAL2	29	0	Crystal 2. XTAL2 is a 6-MHz crystal output. This terminal must be left open when using an oscillator.



# TUSB2036 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE

SLLS372C - MARCH 2000 - REVISED NOVEMBER 2006

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> (see Note 1)	
Input voltage range, V <sub>1</sub>	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub>	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ , $(V_I < 0 \text{ V or } V_I > V_{CC})$	±20 mA
Output clamp current, I <sub>OK</sub> , (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Storage temperature range, T <sub>Stg</sub>	–65°C to 150°C
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# NOTE 3: All voltage levels are with respect to GND.

# recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	3	3.3	3.6	V
Input voltage, TTL/LVCMOS, VI	0		VCC	V
Output voltage, TTL/LVCMOS, VO	0		VCC	V
High-level input voltage, signal-ended receiver, VIH(REC)	2		VCC	V
Low-level input voltage, signal-ended receiver, VIL(REC)			8.0	V
High-level input voltage, TTL/LVCMOS, VIH(TTL)	2		VCC	V
Low-level input voltage, TTL/LVCMOS, V <sub>IL(TTL)</sub>	0		8.0	V
Operating free-air temperature, T <sub>A</sub>	0		70	°C
External series, differential driver resistor, R(DRV)	22 (-5%)		22 (+5%)	Ω
Operating (dc differential driver) high-speed mode, f(OPRH)			12	Mb/s
Operating (dc differential driver) low-speed mode, f(OPRL)			1.5	Mb/s
Common mode, input range, differential receiver, V(ICR)	0.8		2.5	V
Input transition times, t <sub>t</sub> , TTL/LVCMOS	0		25	ns
Junction temperature range, TJ	0		115	°C

# **TUSB2036** 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE

SLLS372C - MARCH 2000 - REVISED NOVEMBER 2006

# electrical characteristics over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
		TTL/LVCMOS	$I_{OH} = -4 \text{ mA}$	V <sub>CC</sub> - 0.5		
Vон	High-level output voltage	LIOD data lines	$R_{(DRV)} = 15 \text{ k}\Omega$ , to GND	2.8		V
		USB data lines	$I_{OH} = -12 \text{ mA (without R}_{(DRV)})$	V <sub>CC</sub> – 0.5		
		TTL/LVCMOS	I <sub>OL</sub> = 4 mA		0.5	
$V_{OL}$	Low-level output voltage	USB data lines	$R(DRV) = 1.5 \text{ k } \Omega \text{ to } 3.6 \text{ V}$		0.3	V
		USB data lines	I <sub>OL</sub> = 12 mA (without R <sub>(DRV)</sub> )		0.5	
\/	Desitive input threehold voltage	TTL/LVCMOS			1.8	V
V <sub>IT+</sub>	Positive input threshold voltage	Single-ended	0.8 V ≤ V <sub>ICR</sub> ≤ 2.5 V		1.8	V
.,	No notive input the opening values	TTL/LVCMOS		0.8		V
V <sub>IT</sub> _	Negative-input threshold voltage	Single-ended	$0.8 \text{ V} \le \text{V}_{1CR} \le 2.5 \text{ V}$	1		V
	Lancet because of the Alice Alice	TTL/LVCMOS		0.3	0.7	V
V <sub>hys</sub>	Input hysteresis† (V <sub>T+</sub> – V <sub>T-</sub> )	Single-ended	0.8 V ≤ V <sub>ICR</sub> ≤ 2.5 V	300	500	mV
	I Park Samuel and a subset assumed	TTL/LVCMOS	V = V <sub>CC</sub> or GND‡		±10	μΑ
loz	High-impedance output current	USB data lines	$0 \text{ A} \leq \text{AO} \leq \text{ACC}$		±10	μΑ
I <sub>I</sub> L	Low-level input current	TTL/LVCMOS	V <sub>I</sub> = GND		-1	μΑ
lіН	High-level input current	TTL/LVCMOS	VI = VCC		1	μΑ
z <sub>o</sub> (DRV)	Driver output impedance	USB data lines	Static VOH or VOL	7.1	19.9	Ω
V <sub>ID</sub>	Differential input voltage	USB data lines	0.8 V ≤ V <sub>ICR</sub> ≤ 2.5 V	0.2		V
	land complete compart		Normal operation		40	mA
ICC	Input supply current		Suspend mode		1	μΑ

<sup>†</sup> Applies for input buffers with hysteresis

# differential driver switching characteristics over recommended ranges of operating free-air temperature and supply voltage, C<sub>L</sub> = 50 pF (unless otherwise noted)

# full speed mode

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t <sub>r</sub>	Transition rise time for DP or DM	See Figure 1 and Figure 2	4	20	ns
tf	Transition fall time for DP or DM	See Figure 1 and Figure 2	4	20	ns
t(RFM)	Rise/fall time matching§	$(t_{\rm f}/t_{\rm f}) \times 100$	90%	110%	
Vo(CRS)	Signal crossover output voltage§		1.3	2.0	V

<sup>§</sup> Characterized only. Limits approved by design and are not production tested

## low speed mode

	PARAMETER	TEST CONDITIONS			MAX	UNIT
t <sub>r</sub> Transition rise time for DP or DM§		$C_L = 200 \text{ pF to } 600 \text{ pF},$	See Figure 1 and Figure 2	75	300	ns
t <sub>f</sub>	Transition fall time for DP or DM§	$C_L = 200 \text{ pF to } 600 \text{ pF},$	See Figure 1 and Figure 2	75	300	ns
t(RFM)	Rise/fall time matching§	(t <sub>r</sub> /t <sub>f</sub> ) x 100		80%	120%	
VO(CRS)	Signal crossover output voltage§	C <sub>L</sub> = 200 pF to 600 pF		1.3	2.0	V

<sup>§</sup> Characterized only. Limits approved by design and are not production tested



<sup>‡</sup> Applies for open drain buffers

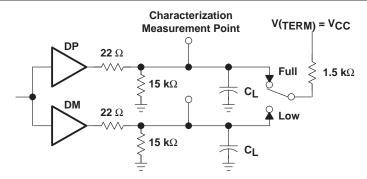
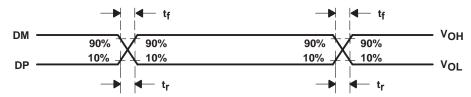


Figure 1. Differential Driver Switching Load



NOTE: The  $t_r/t_f$  ratio is measured as  $t_r(DP)/t_f(DM)$  and  $t_r(DM)/t_f(DP)$  at each crossover point.

Figure 2. Differential Driver Timing Waveforms

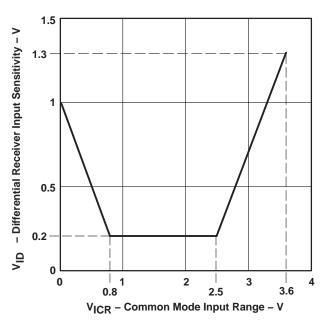


Figure 3. Differential Receiver Input Sensitivity vs Common Mode Input Range

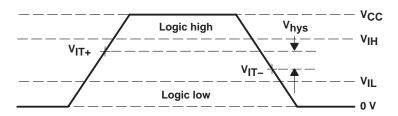


Figure 4. Single-Ended Receiver Input Signal Parameter Definitions



## APPLICATION INFORMATION

A major advantage of USB is the ability to connect 127 functions configured in up to 6 logical layers (tiers) to a single personal computer (see Figure 5).

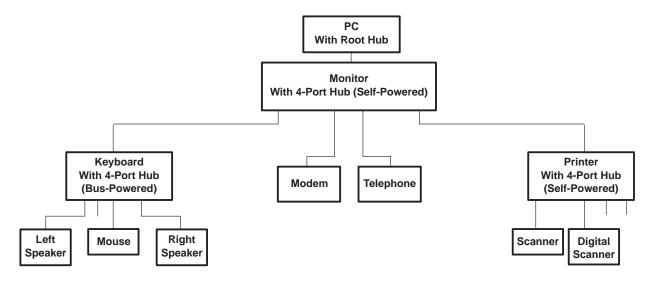


Figure 5. USB-Tiered Configuration Example

Another advantage of USB is that all peripherals are connected using a standardized four-wire cable that provides both communication and power distribution. The power configurations are bus-powered and self-powered modes. The maximum current that may be drawn from the USB 5-V line during power up is 100 mA. For the bus-powered mode, a hub can draw a maximum of 500 mA from the 5-V line of the USB cable. A bus-powered hub must always be connected downstream to a self-powered hub unless it is the only hub connected to the PC and there are no high-powered functions connected downstream. In the self-powered mode, the hub is connected to an external power supply and can supply up to 500 mA to each downstream port. High-powered functions may draw a maximum of 500 mA from each downstream port and may only be connected downstream to self-powered hubs. Per the USB specification, in the bus-powered mode, each downstream port can provide a maximum of 100 mA of current, and in the self-powered mode, each downstream port can provide a maximum of 500 mA of current.

Both bus-powered and self-powered hubs require overcurrent protection for all downstream ports. The two types of protection are individual-port management (individual-port basis) or ganged-port management (multiple-port basis). Individual-port management requires power-management devices for each individual downstream port, but adds robustness to the USB system because, in the event of an overcurrent condition, the USB host only powers down the port that has the condition. The ganged-port configuration uses fewer power management devices and thus has lower system costs, but in the event of an overcurrent condition on any of the downstream ports, all the ganged ports are disabled by the USB host.

Using a combination of the BUSPWR and EEDATA/GANGED inputs, the TUSB2036 supports four modes of power management: bus-powered hub with either individual-port power management or ganged-port power management, and the self-powered hub with either individual-port power management or ganged-port power management. Texas Instruments supplies the complete hub solution because we offer this TUSB2036, the TUSB2043/TUSB2046 (4-port), the TUSB2077A (7-port), and the TUSB2140B (4-port with I<sup>2</sup>C) hubs along with the power-management devices needed to implement a fully USB Specification 1.1 compliant system.



## APPLICATION INFORMATION

# **USB** design notes

The following sections provide block diagram examples of how to implement the TUSB2036 device. Please note, even though no resistors are shown, pullup, pulldown, and series resistors must still be used to properly implement this device.

Figure 6 is a block diagram example of how to connect the external EEPROM if a custom product ID and vendor ID are desired.

Figure 7 is an example of how to generate the 6-MHz clock signal. Figure 8 shows the EEPROM read operation timing diagram. Figures 9, 10, and 11 illustrate how to connect the TUSB2036 device for different power source and port power-management combinations.

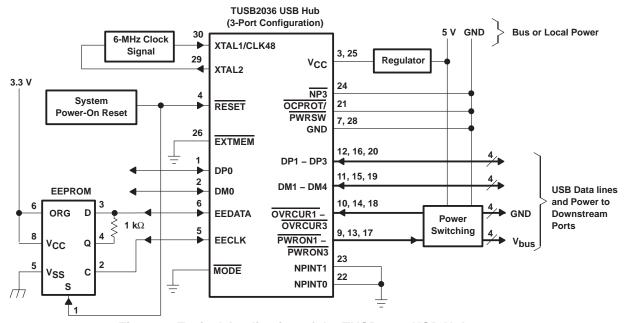
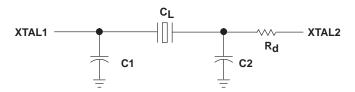


Figure 6. Typical Application of the TUSB2036 USB Hub



NOTE A: Figure 7 assumes a 6 MHz fundamental crystal that is parallel loaded. The component values of C1, C2 and R<sub>d</sub> were determined using a crystal from Fox Electronics – part number HC49U–6.00MHz30\50\0  $\pm$ 70\20 which means  $\pm$ 30 ppm at 25°C and 50 ppm from 0°C to 70°C. The characteristics for the crystal are load capacitance (C<sub>L</sub>) of 20 pF, maximum shunt capacitance (C<sub>0</sub>) of 7 pF and the maximum ESR of 50  $\Omega$ . In order to insure enough negative resistance, use C1 = C2 = 27 pF. The resistor R<sub>d</sub> is used to trim the gain, and R<sub>d</sub> = 1.5 k $\Omega$  is recommended.

Figure 7. Crystal Tuning Circuit



#### **APPLICATION INFORMATION**

## programming the EEPROM

An SGS Thompson M93C46 EEPROM, or equivalent, stores the programmable VID and PID. When the EEPROM interface is enabled ( $\overline{\text{EXTMEM}} = 0$ ), the EECLK and EEDATA are internally pulled down (100  $\mu$ A) inside the TUSB2036. The internal pulldowns are disabled when the EEPROM interface is disabled ( $\overline{\text{EXTMEM}} = 1$ ).

The EEPROM is programmed with the three 16-bit locations as shown in Table 1. Connecting terminal 6 of the EEPROM high (ORG = 1) organizes the EEPROM memory into 64×16-bit words.

**Table 2. EEPROM Memory Map** 

ADDRESS	D15	D14	D13	D12-D8	D7-D0		
00000	0	GANGED	0	0 0000	0000 0000		
00001	VID High-byte VID Low-byte						
00010	PID High-byte PID Low-byte						
	XXXXXXXX						

The D and Q signals of the EEPROM must be tied together using a 1-k $\Omega$  resistor with the common I/O operations forming a single-wire bus. After system power-on reset, the TUSB2036 performs a one-time access read operation from the EEPROM if the EXTMEM terminal is pulled low and the chip select(s) of the EEPROM is connected to the system power-on reset. Initially, the EEDATA terminal is driven by the TUSB2036 to send a start bit (1), which is followed by the read instruction (10) and the starting-word address (00000). Once the read instruction is received, the instruction and address are decoded by the EEPROM, which then sends the data to the output shift register. At this point, the hub stops driving the EEDATA terminal and the EEPROM starts driving. A dummy (0) bit is then output and the first three 16-bit words in the EEPROM are output with the most significant bit (MSB) first.

The output data changes are triggered by the rising edge of the clock provided by the TUSB2036 on the EECLK terminal. The SGS-Thompson M93C46 EEPROM is recommended because it advances to the next memory location by automatically incrementing the address internally. Any EEPROM used must have the automatic internal address advance function. After reading the three words of data from the EEPROM, the TUSB2036 puts the EEPROM interface into a high-impedance condition (pulled down internally) to allow other logic to share the EEPROM. The EEPROM read operation is summarized in Figure 8. For more details on EEPROM operation, refer to SGS-Thompson Microelectronics M93C46 Serial Microwire Bus EEPROM data sheet.



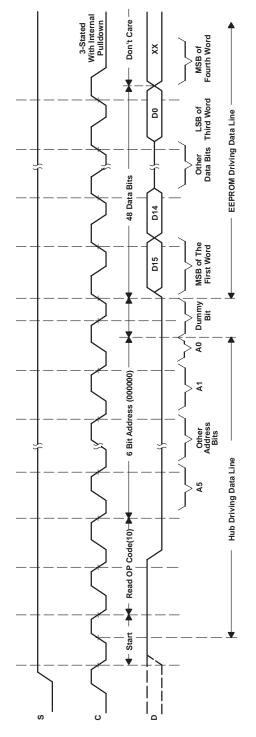


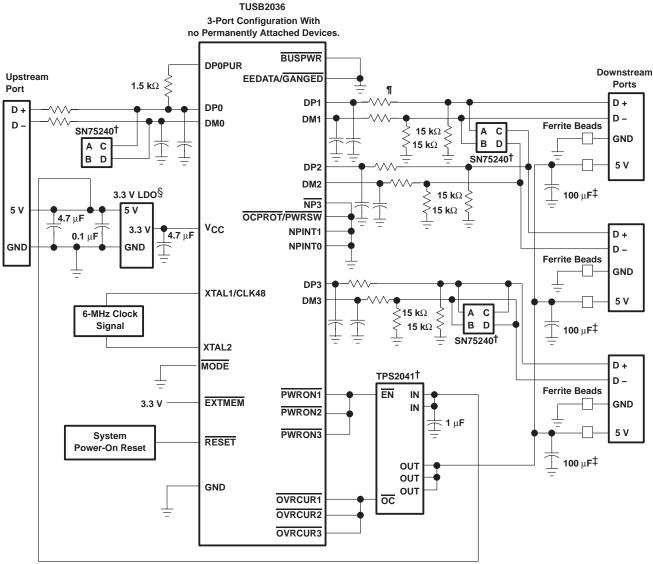
Figure 8. EEPROM Read Operation Timing Diagram



## **APPLICATION INFORMATION**

## bus-powered hub, ganged-port power management

When used in bus-powered mode, the TUSB2036 supports up to three downstream ports by controlling a TPS2041 device which is capable of supplying 100 mA of current to each downstream port. Bus-powered hubs must implement power switching to ensure current demand is held below 100 mA when the hub is hot-plugged into the system. Utilizing the TPS2041 for ganged-port power management provides overcurrent protection for the downstream ports. The SN75240 transient suppressors reduce inrush current and voltage spikes on the data lines. The  $\overline{\text{OVRCUR}}$  signals must be tied together for a ganged operation.



<sup>†</sup> TPS2041 and SN75240 are Texas Instruments devices.

Figure 9. TUSB2036 Bus-Powered Hub, Ganged-Port Power-Management Application



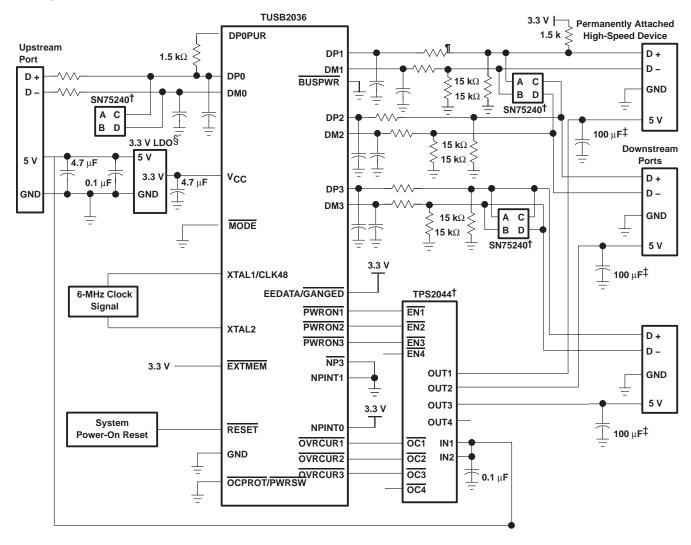
<sup>‡ 120</sup> μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

<sup>§</sup> LDO is a 5-V-to-3.3-V voltage regulator.

<sup>¶</sup> All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

## **APPLICATION INFORMATION**

bus-powered hub with a permanently attached high-speed device, ganged-port power management



<sup>†</sup> TPS2042 and SN75240 are Texas Instruments devices. Two TPS2042 devices can be substituted for the TPS2044.

Figure 10. TUSB2036 Bus-Powered Hub With a Permanently Attached High-Speed Device, Individual-Port Power-Management Application



<sup>‡120</sup> μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

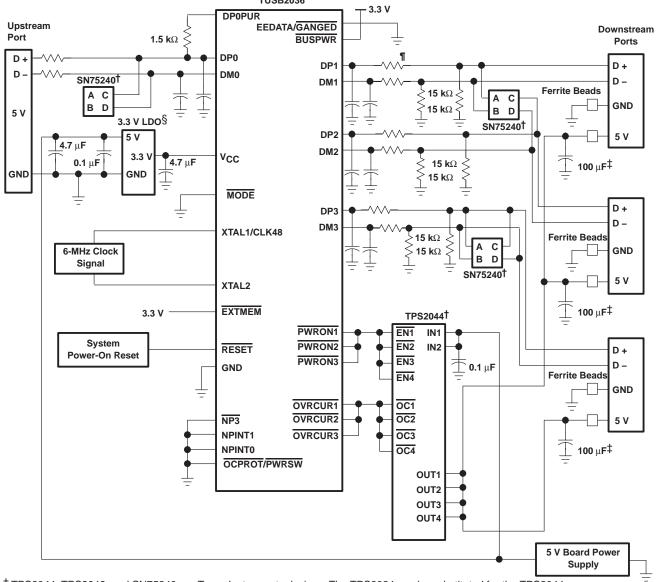
<sup>§</sup> LDO is a 5-V-to-3.3-V voltage regulator

<sup>¶</sup> All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

#### **APPLICATION INFORMATION**

## self-powered hub, ganged-port power management

The TUSB2036 can also be implemented for ganged-port power management in a self-powered configuration. The implementation is very similar to the bus-powered example with the exception that a self-powered port supplies 500 mA of current to each downstream port. The overcurrent protection can be provided by a TPS2044 quad device or a TPS2024 single power switch.



<sup>†</sup> TPS2044, TPS2042, and SN75240 are Texas Instruments devices. The TPS2024 can be substituted for the TPS2044.

Figure 11. TUSB2036 Self-Powered Hub, Ganged-Port Power-Management Application



<sup>&</sup>lt;sup>‡</sup> 120 μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

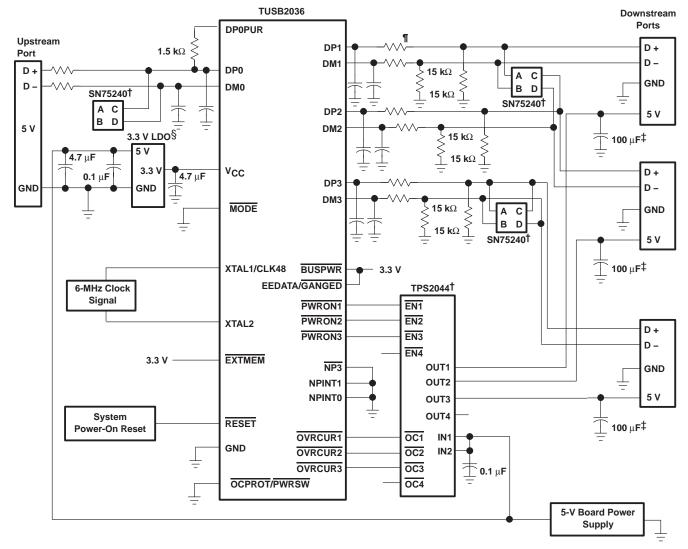
<sup>§</sup> LDO is a 5-V-to-3.3-V voltage regulator

<sup>¶</sup> All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

#### **APPLICATION INFORMATION**

## self-powered hub, individual-port power management

In a self-powered configuration, the TUSB2036 can be implemented for individual-port power management when used with the TPS2044 because it is capable of supplying 500 mA of current to each downstream port and can provide current limiting on a per-port basis. When the hub detects a fault on a downstream port, power is removed from only the port with the fault and the remaining ports continue to operate normally. Self-powered hubs are required to implement overcurrent protection and report overcurrent conditions. The SN75240 transient suppressors reduce inrush current and voltage spikes on the data lines.



<sup>†</sup> TPS2042 and SN75240 are Texas Instruments devices. Two TPS2042 devices can be substituted for the TPS2044.

Figure 12. TUSB2036 Self-Powered Hub, Individual-Port Power-Management Application



<sup>‡120</sup> μF per hub is the minimum required per the USB specification, version 1.1. However, TI recommends a 100-μF, low ESR, tantalum capacitor per port for immunity to voltage droop.

<sup>§</sup> LDO is a 5-V-to-3.3-V voltage regulator

<sup>¶</sup> All USB DP, DM signal pairs require series resistors of approximately 27 Ω to ensure proper termination. An optional filter capacitor of about 22 pF is recommended for EMI suppression. This capacitor, if used, must be placed between the hub pin and the series resistor, as per section 7.1.6 of the USB specification.

# **TUSB2036** 2/3-PORT HUB FOR THE UNIVERSAL SERIAL BUS WITH OPTIONAL SERIAL EEPROM INTERFACE SLLS372B - MARCH 2000 - REVISED JUNE 2005

# **Revision History**

DATE	REV	PAGE	SECTION	DESCRIPTION			
		6 Terminal Functions table		Added sentence to OVRCUR1 – OVRCUR3 description			
6/22/05	В	13	programming the EEPROM	Changed EEPROM memory map address 00000 description			
12/13/04	Α	_		Unknown changes			
3/16/00	*	_		Original version			

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.







.com 5-Feb-2007

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TUSB2036VF	ACTIVE	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TUSB2036VFG4	ACTIVE	LQFP	VF	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TUSB2036VFR	ACTIVE	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
TUSB2036VFRG4	ACTIVE	LQFP	VF	32	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



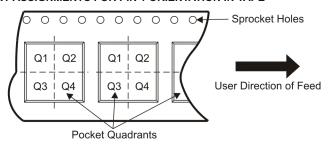
# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

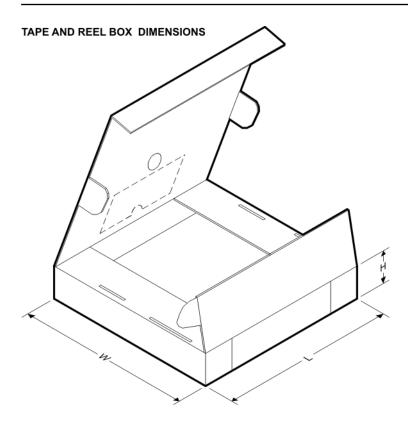
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TUSB2036VFR	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2
TUSB2036VFRG4	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2



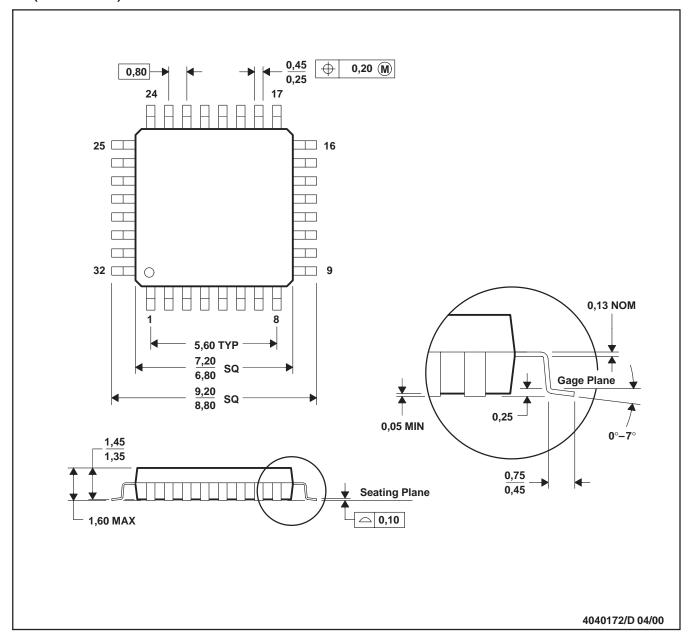


### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TUSB2036VFR	LQFP	VF	32	1000	346.0	346.0	41.0
TUSB2036VFRG4	LQFP	VF	32	1000	346.0	346.0	41.0

# VF (S-PQFP-G32)

## PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

## **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com microcontroller.ti.com Microcontrollers www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated